

Chemically modified reduced graphene oxide (CMrGO)-based Electrodynamic Dust Shield (EDS) devices for lunar dust mitigation

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rGO + EDS: Patterned substrates



Highlights:

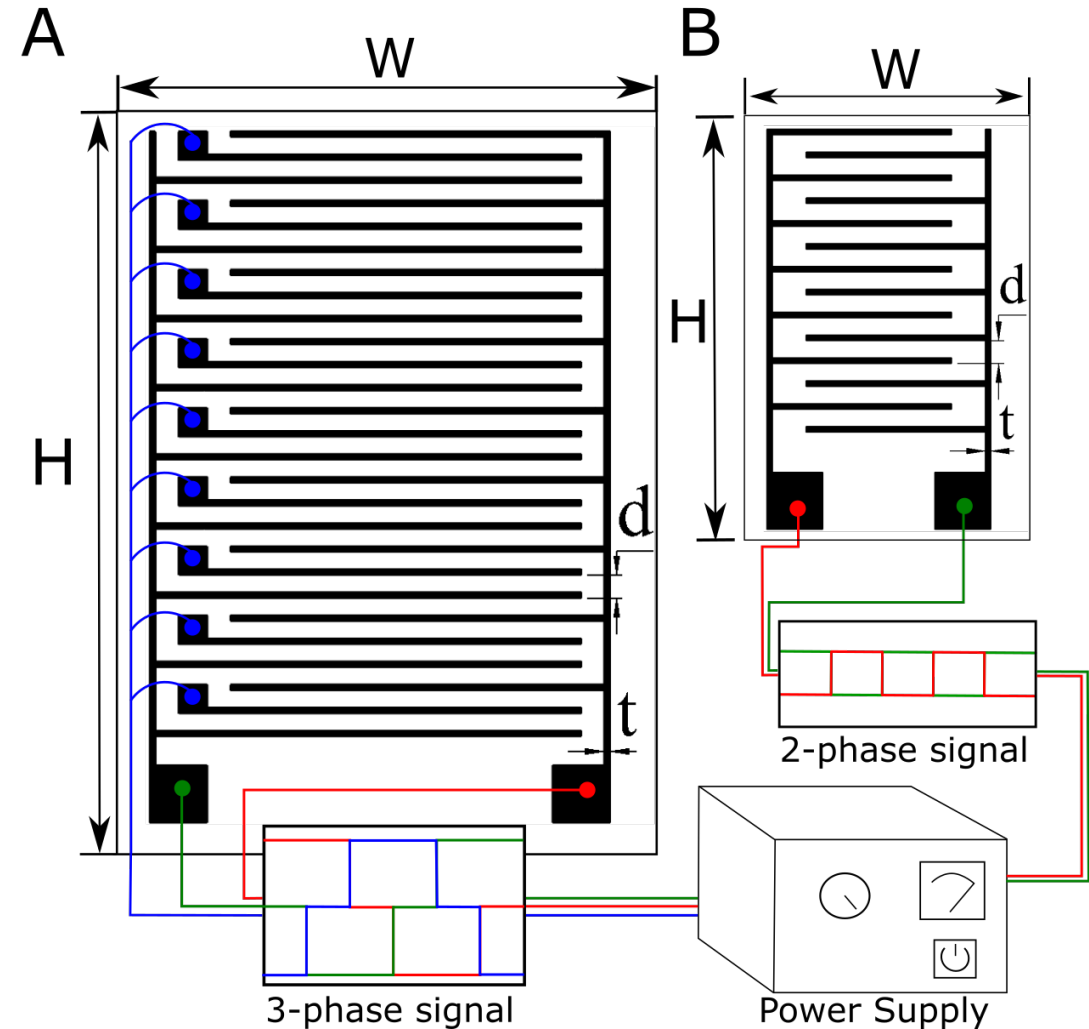
- Spray-coated EDS systems were produced using a conductive nanocomposite material (CMrGO)
- Both 2-phase and 3-phase device configurations efficiently removed >80% of deposited dust
- The 2-phase devices were cleaned at ~50% lower voltage when illuminated with UV light
- Using a dielectric cap eliminates electrical discharges on the surface



EDS Basics

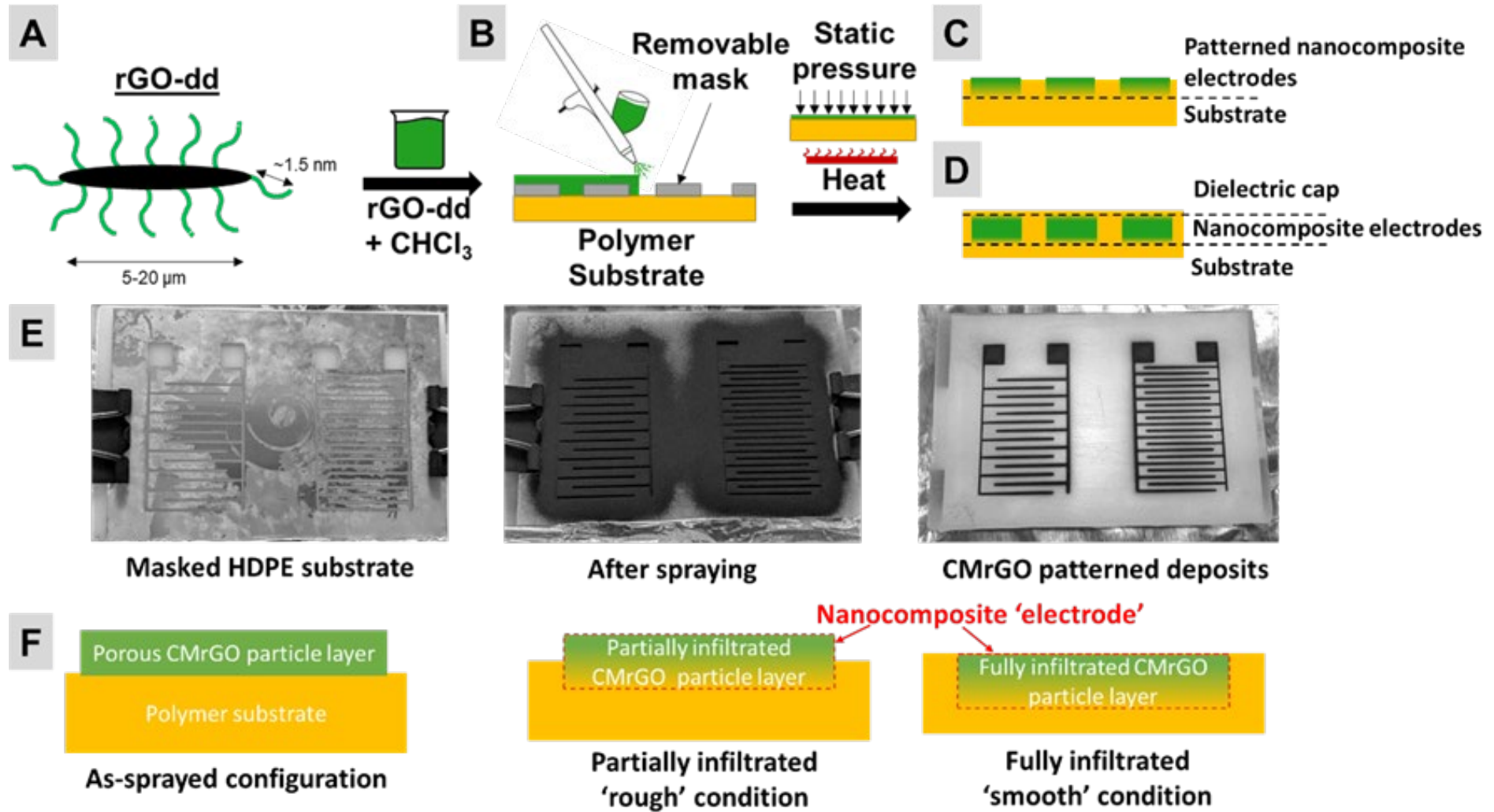


- The 2-phase devices use 10 Hz square waves 180 out of phase
 - A standing wave potential is generated above the device surface for 2-phase
- 3-phase devices use a Moesner and Higuchi waveform
 - A traveling wave is formed above 3-phase devices
- $H \times W = 2 \times 1.5$ in (2p) and 3×2 in (3p)
Electrode trace thickness $t = 0.5$ mm
Inter-electrode spacings $d = 2$ mm





Device Fabrication

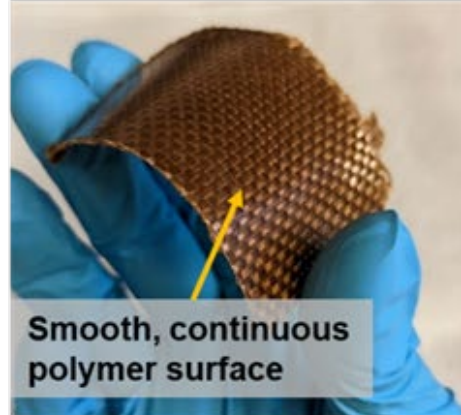
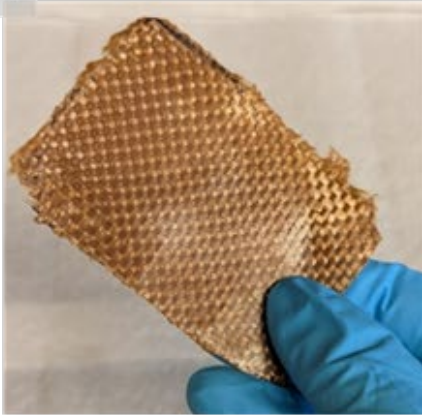


Schaible, M. J., Sjolund, K. G., Ryan, E. A., Shofner, M. L., Reynolds, J. R., Linsey, J. S., & Orlando, T. M. (2023). Performance of chemically modified reduced graphene oxide (CMrGO) in lunar electrodynamic dust shield (EDS) applications. *Acta Astronautica*, 211, 674-683.



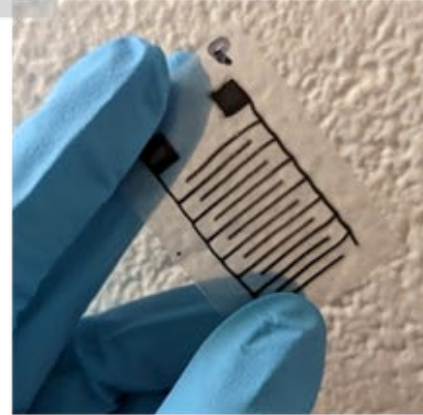
Device Fabrication

A Zylon[®] fabric embedded in thermoplastic polysulfone

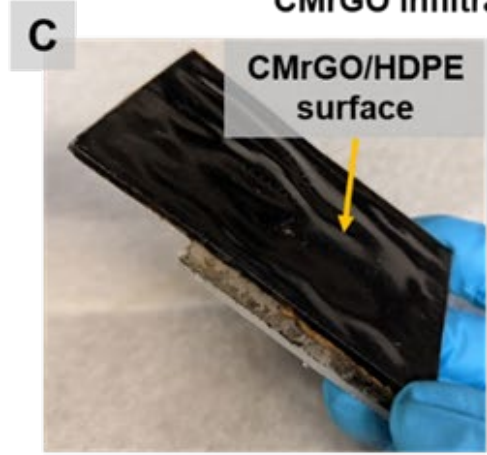


Smooth, continuous polymer surface

B CMrGO device fabricated on 3mil HDPE film

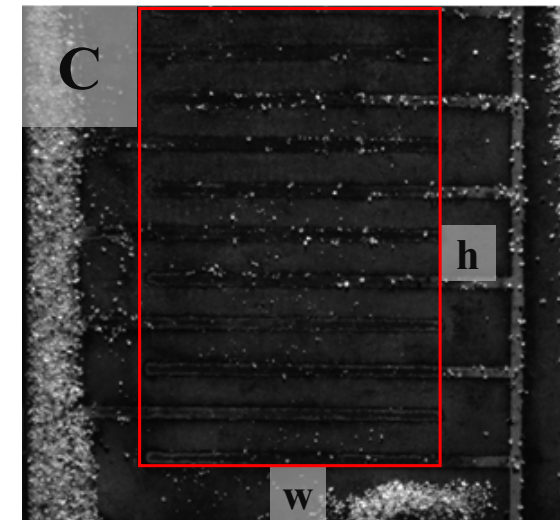
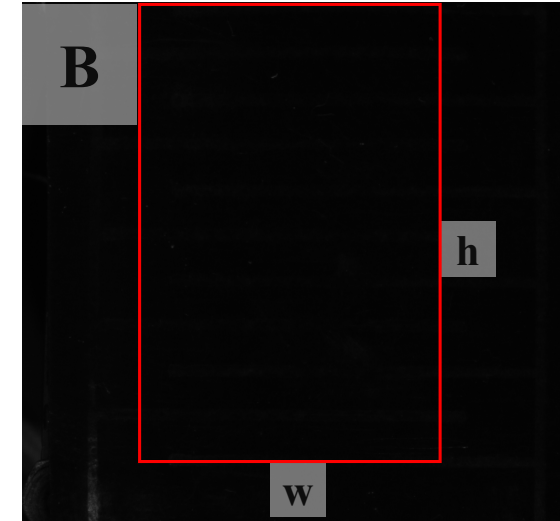
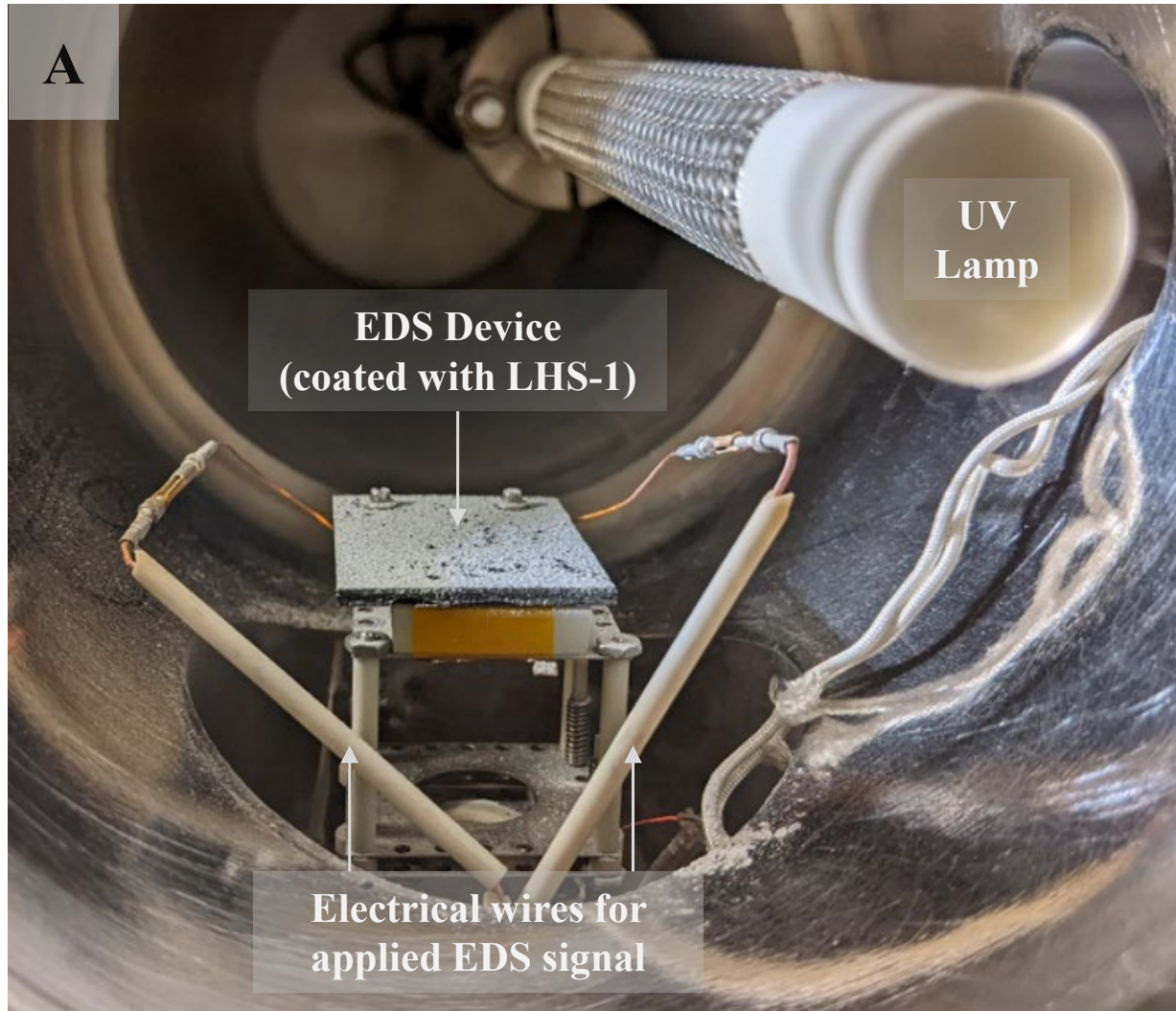


Zylon[®] fabric embedded in a film of HDPE with a CMrGO infiltrated coating





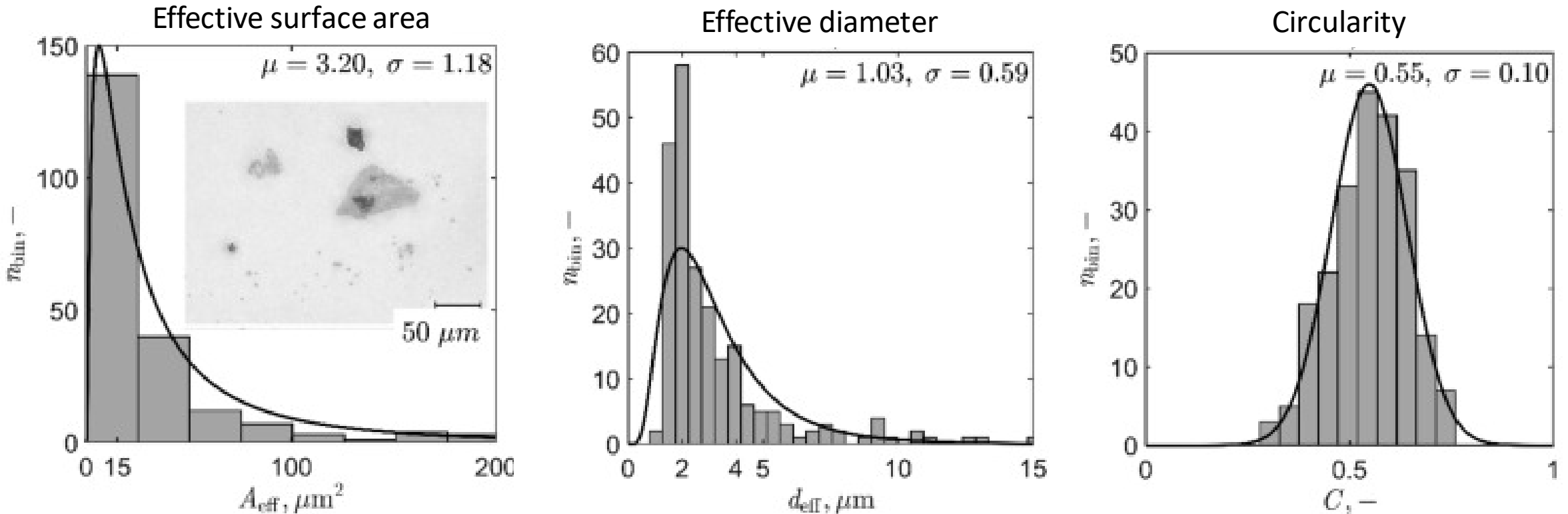
EDS System





Dust Characteristics

Simulants are compositionally and physically like lunar regolith.
Size and shape distributions for LHS-1 from optical microscopy images.



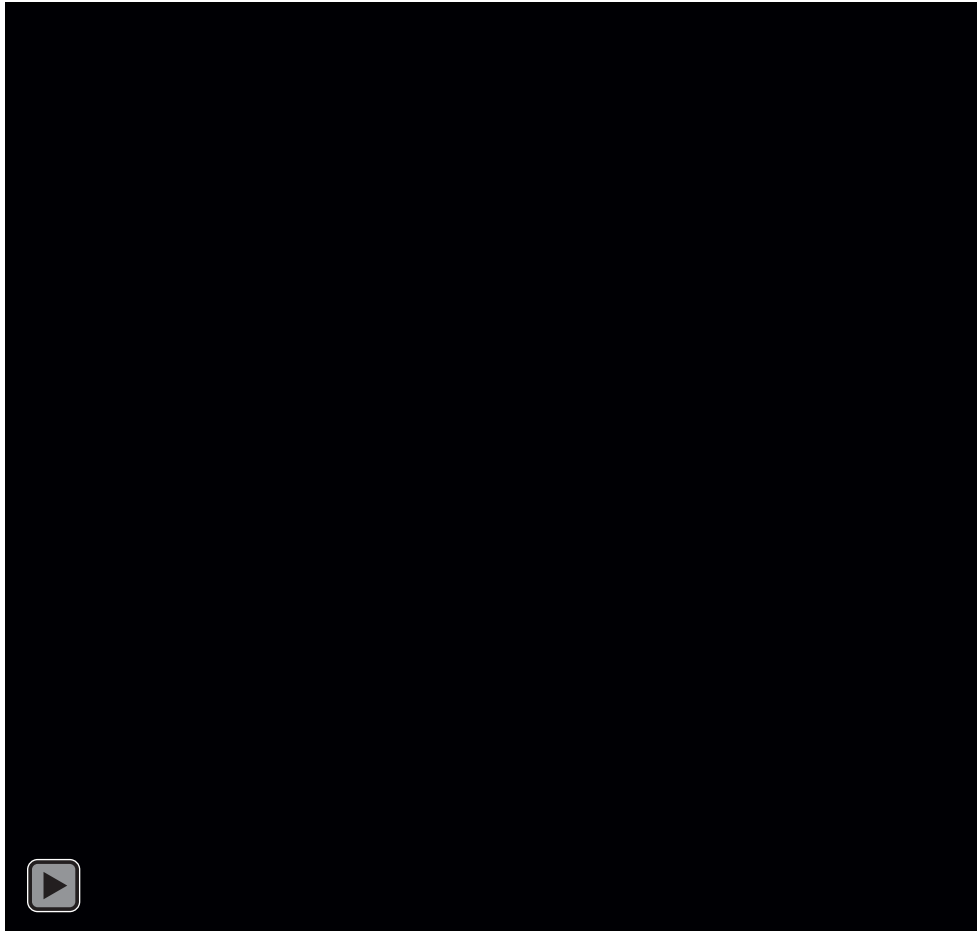
The μ and σ correspond to the mean and standard deviation of the fitted distribution.



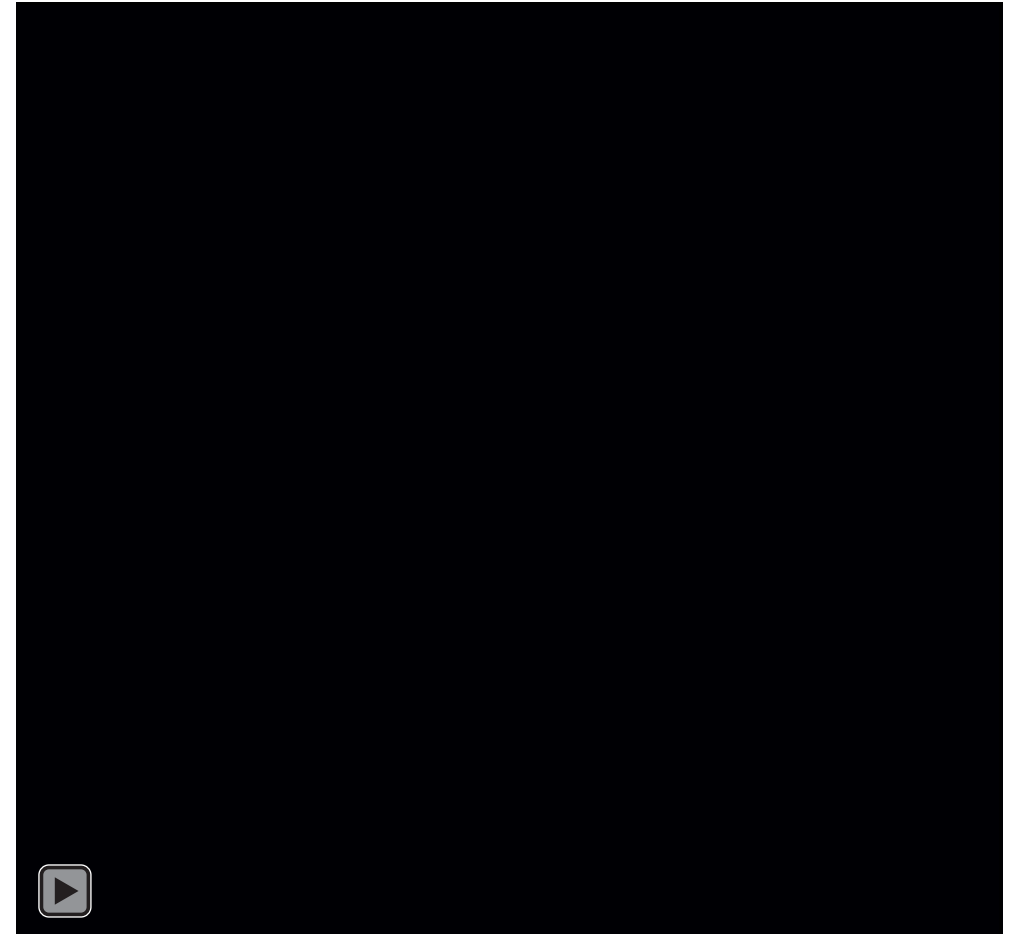
Rough 2-phase devices



1st dust deposition

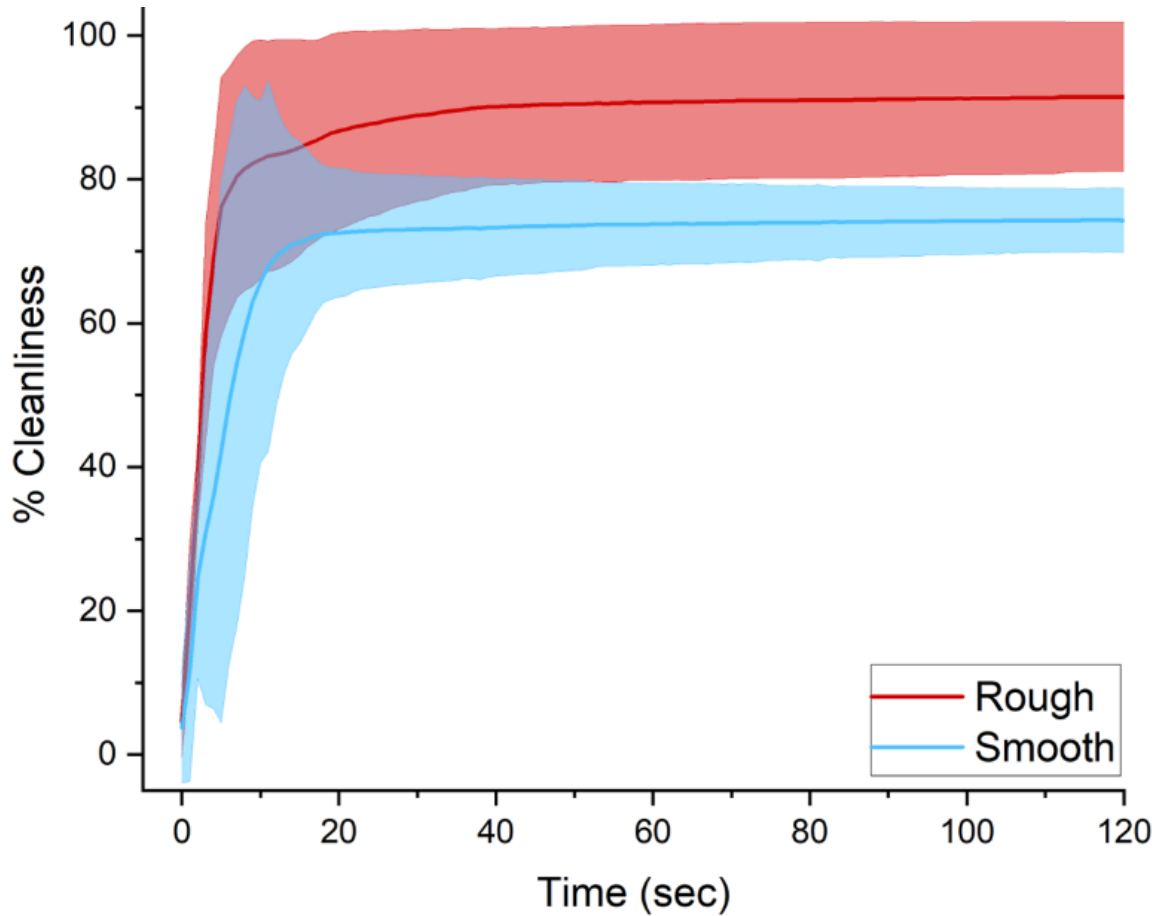


4th dust deposition





Bare 2-phase devices



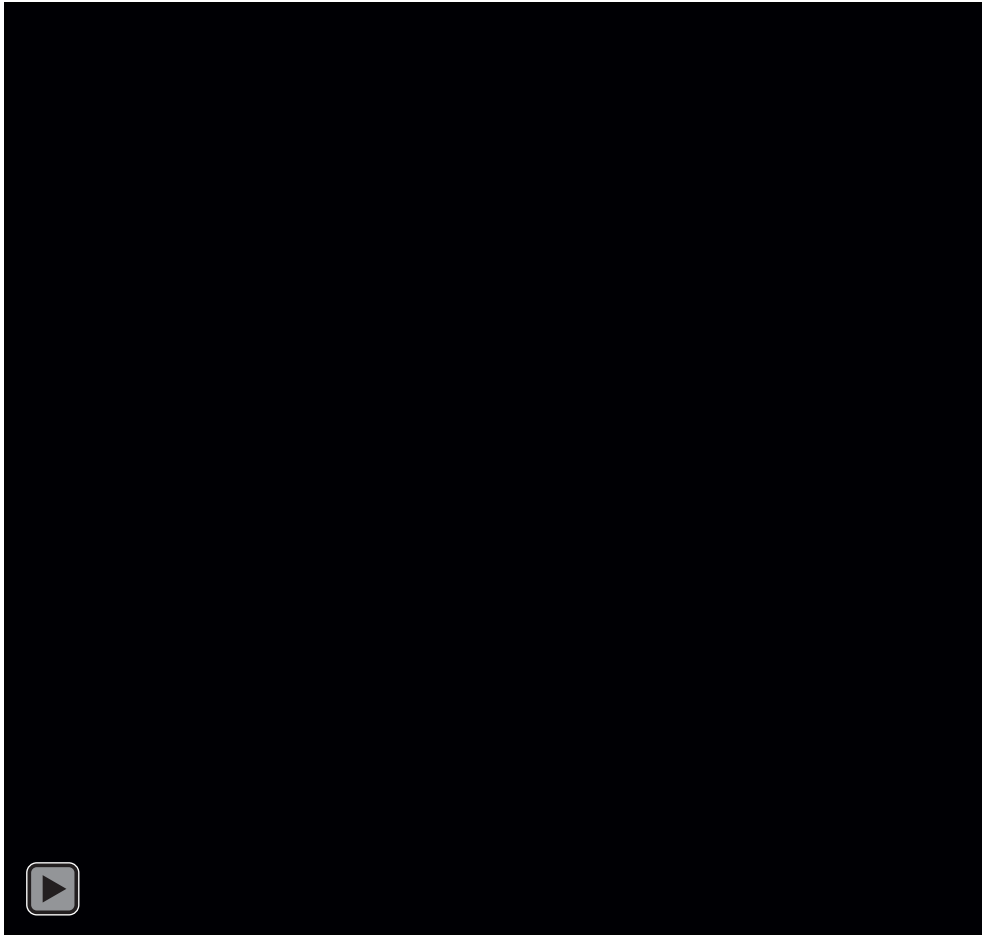
- Dust is efficiently and repeatably removed from 2-phase CMrGO EDS devices
 - A minimum voltage of 1000 V is required for the rough condition
 - A minimum of 2000 V is required for the smooth
- Discharges/dielectric breakdown occurs for several seconds after EDS activation
 - Persistent hot-spots lead to trace failure
 - Smooth devices have fewer discharges and less degradation
 - But worse performance



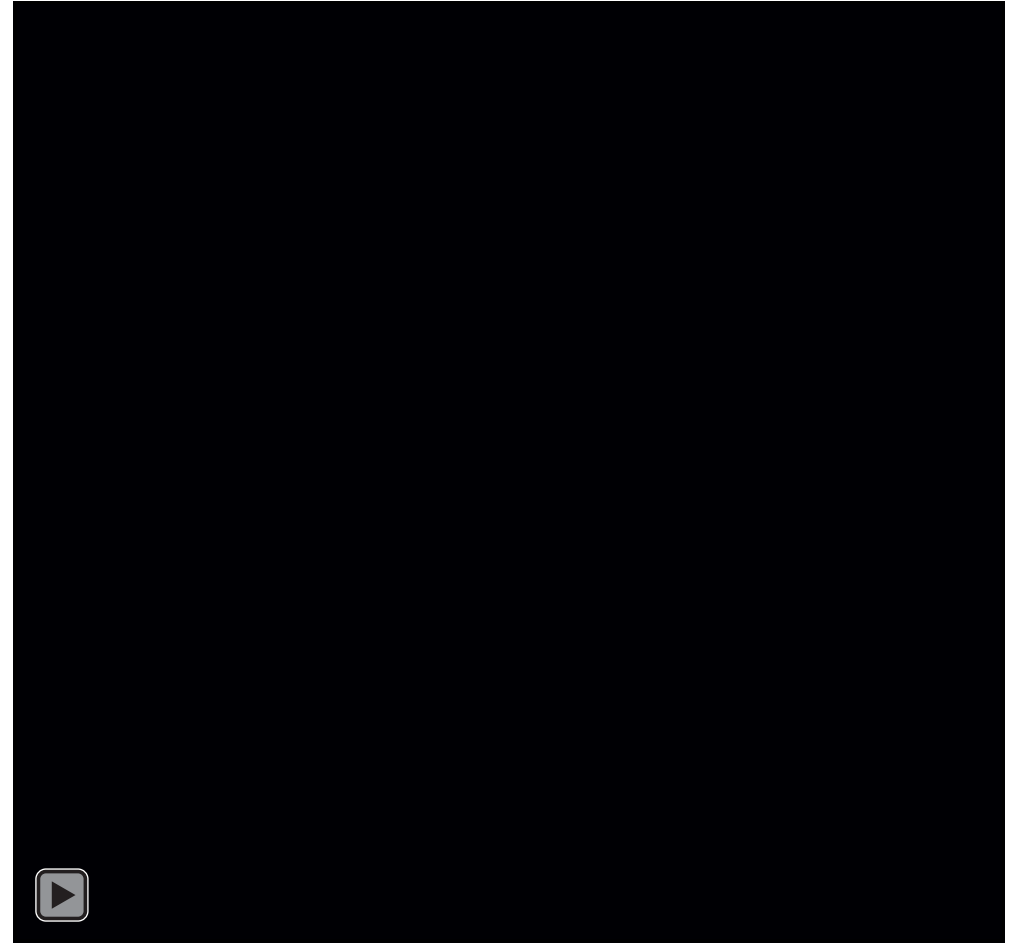
Smooth 2-phase devices



1st dust deposition



3rd dust deposition

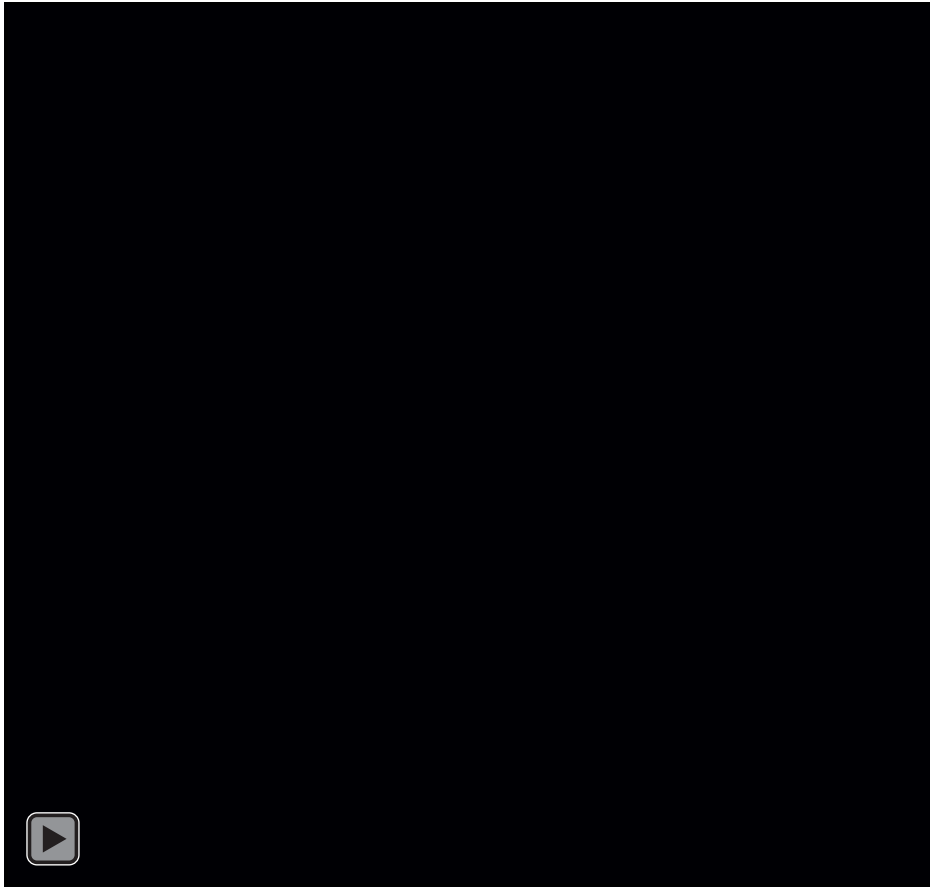




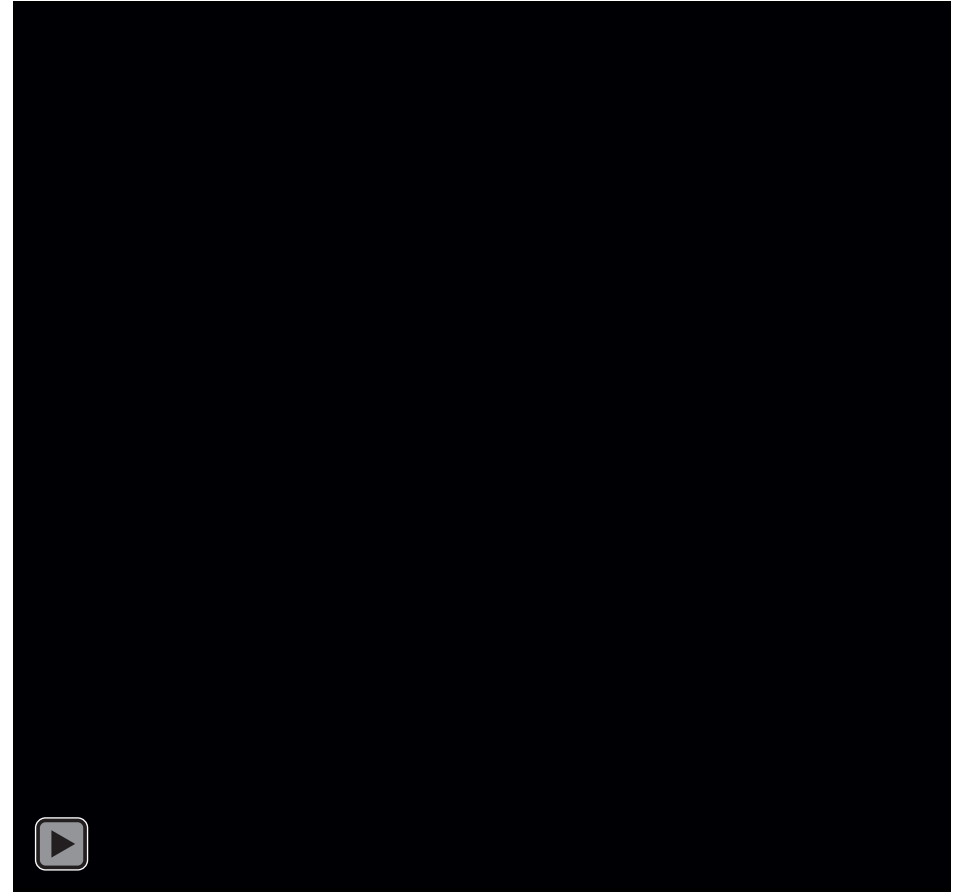
Rough 2-phase devices + UV



1st dust deposition

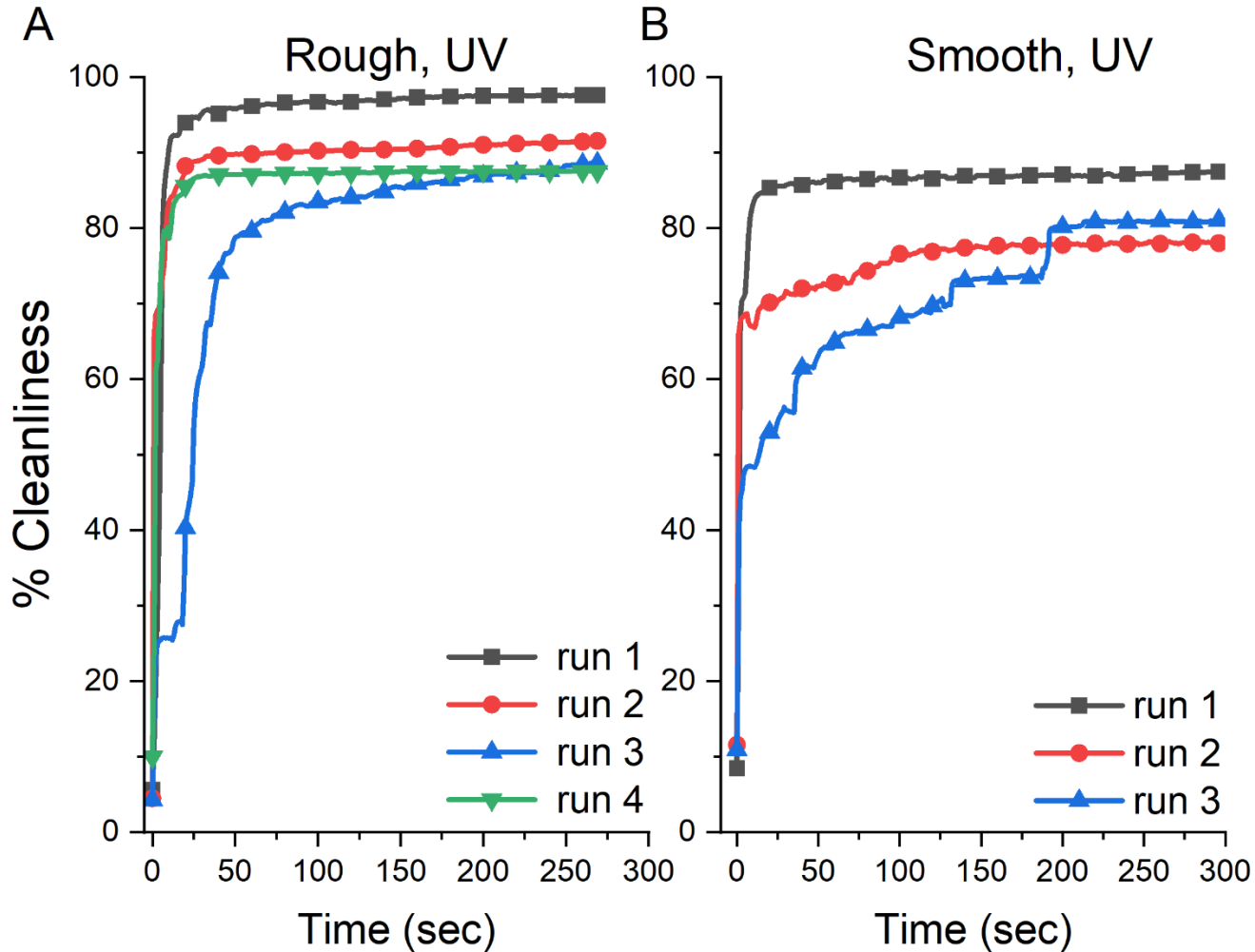


6th dust deposition





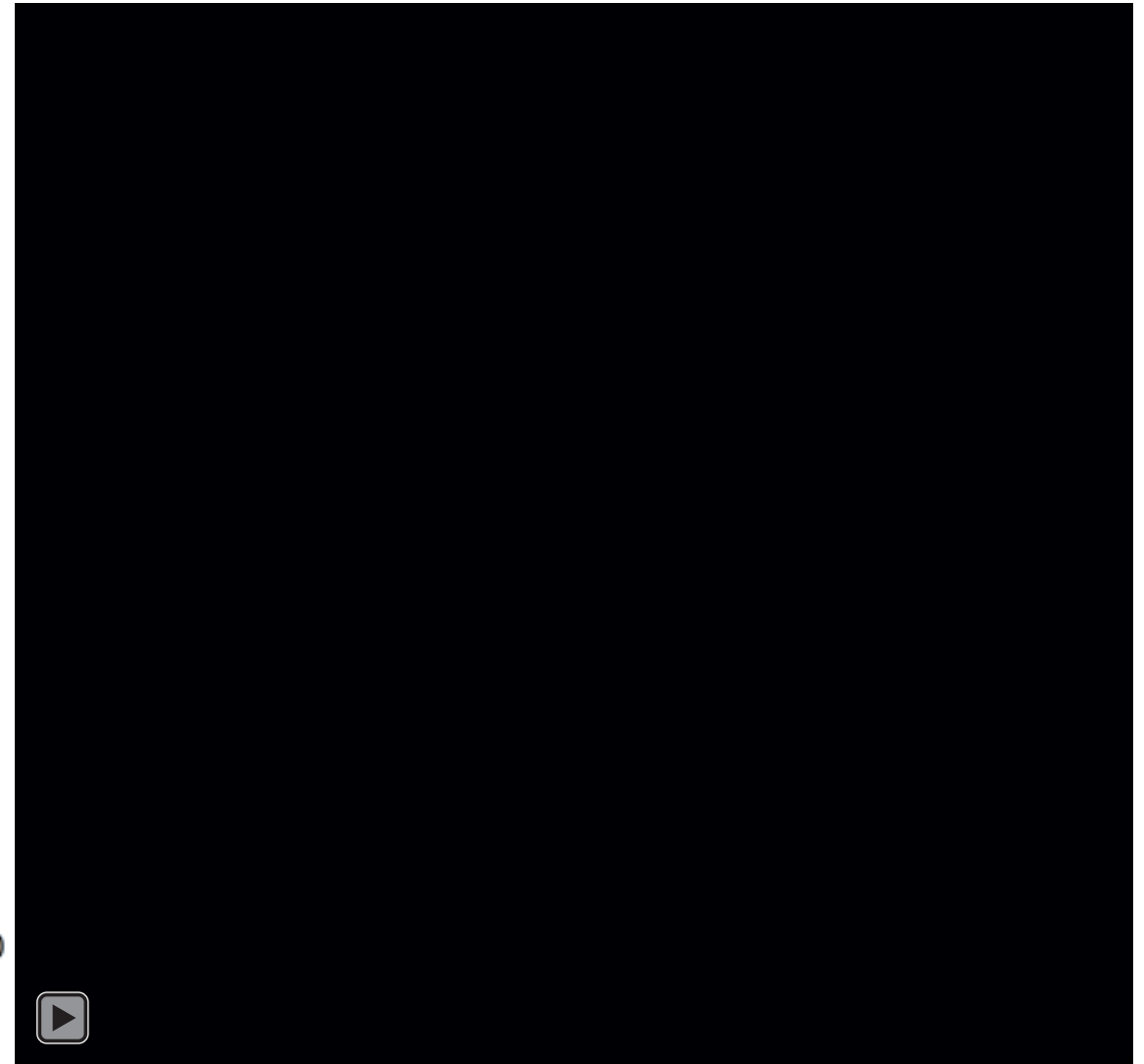
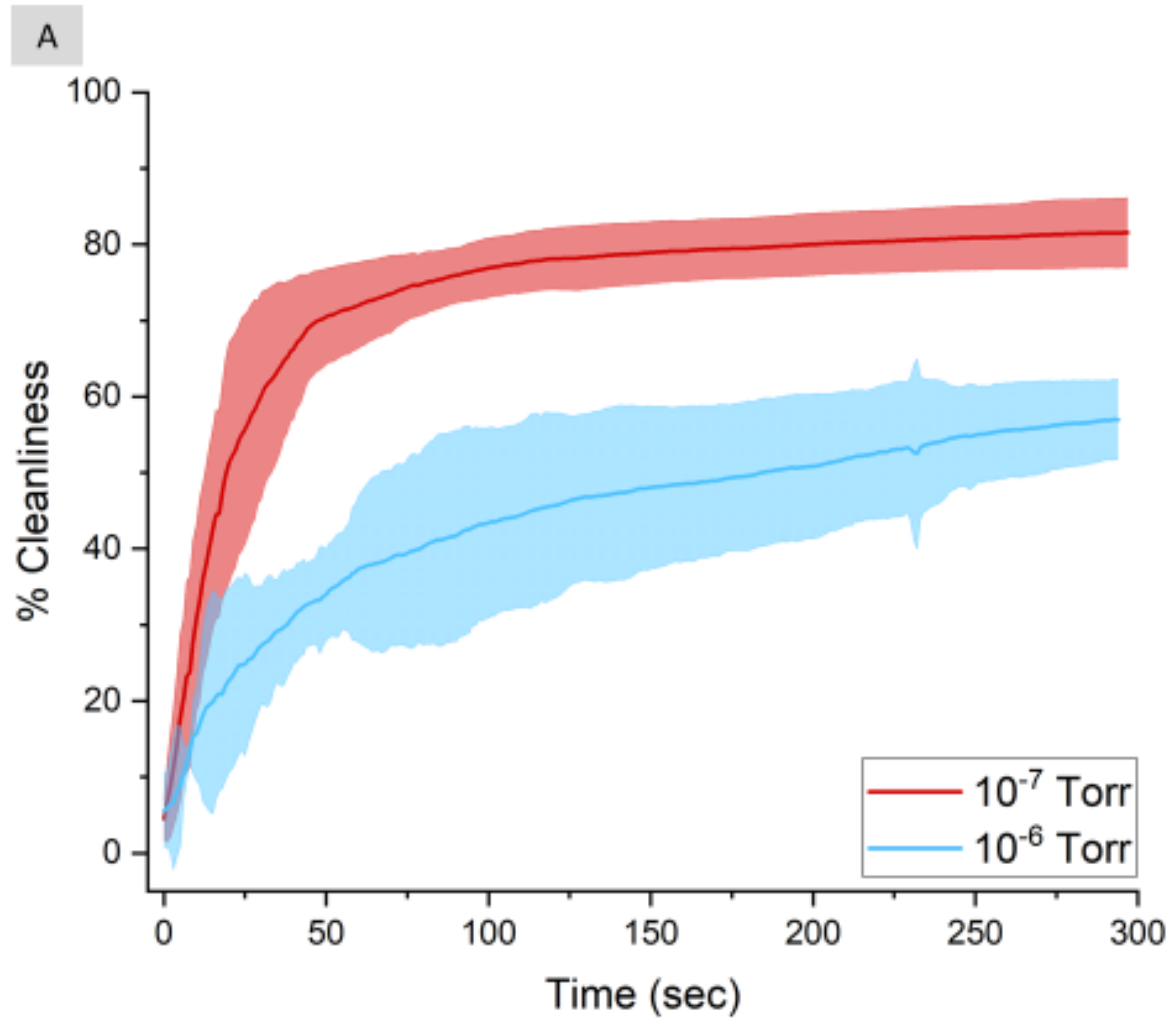
Bare 2-phase devices + UV



- Dust cleared at 800 V, for the rough configuration
- Cleared at 1000V for the smooth configuration
- The dust surface was UV illuminated at 5 sec intervals to avoid heating
- UV illumination caused the devices to degrade more rapidly

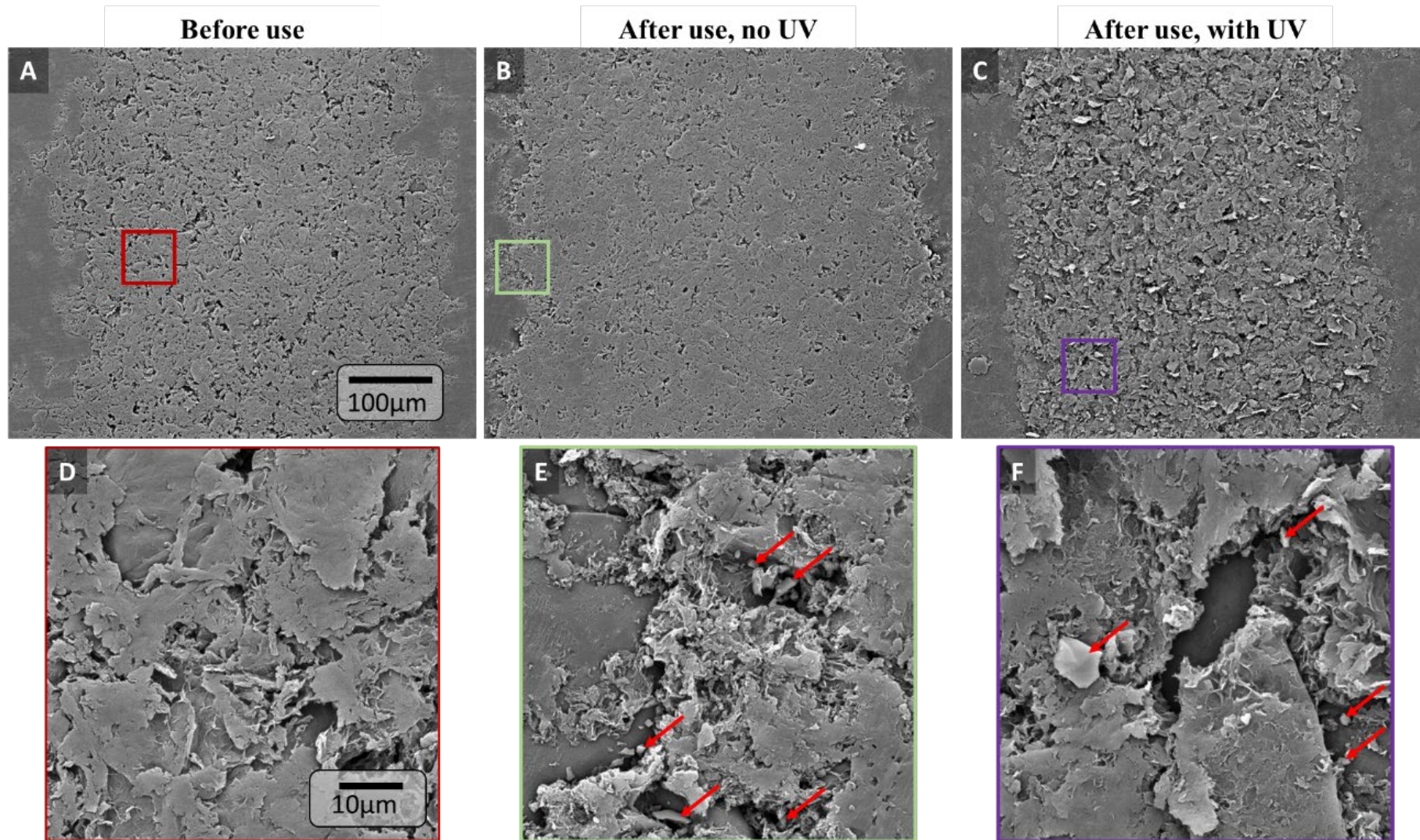


Bare 3-phase devices



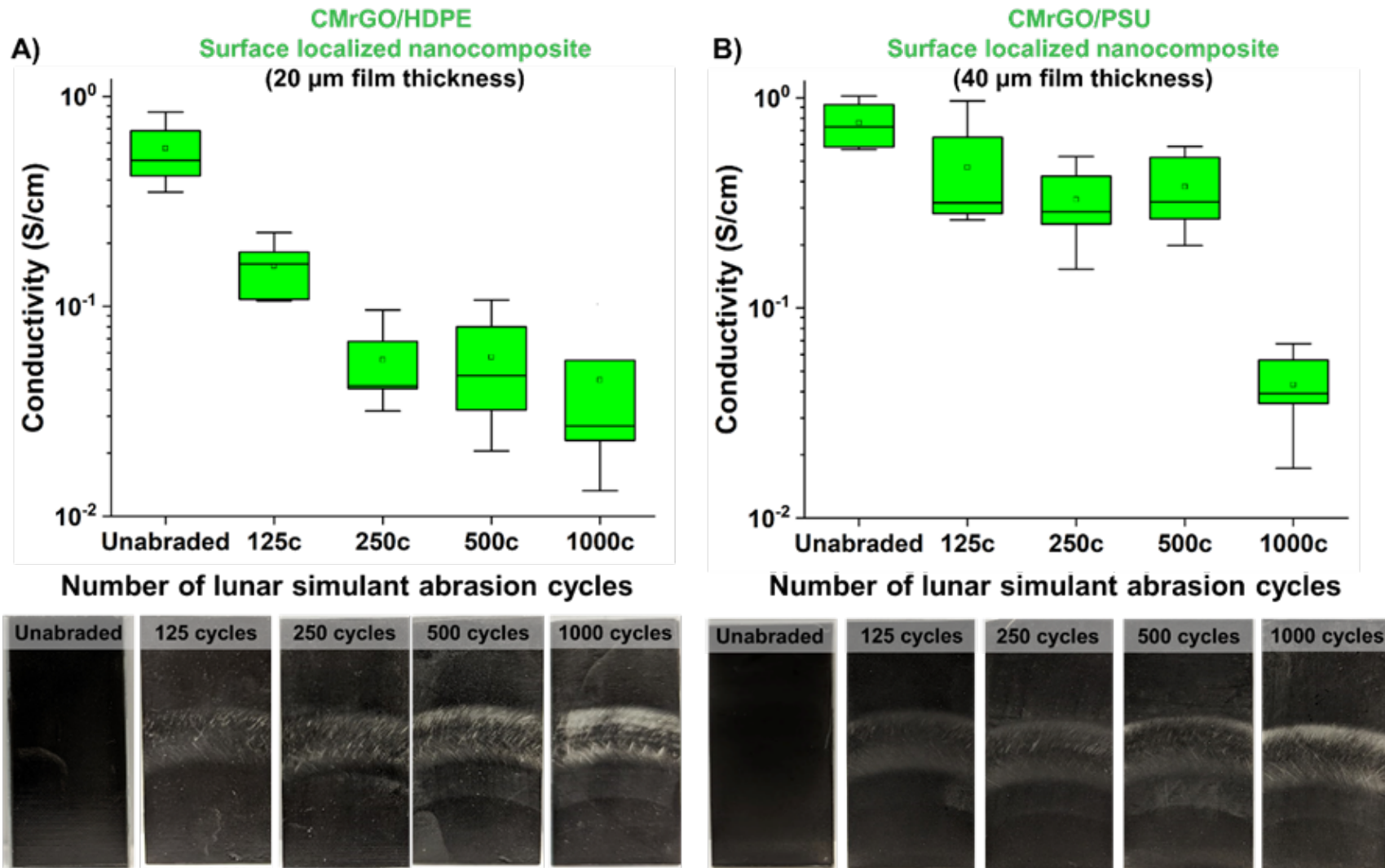


Materials Effects



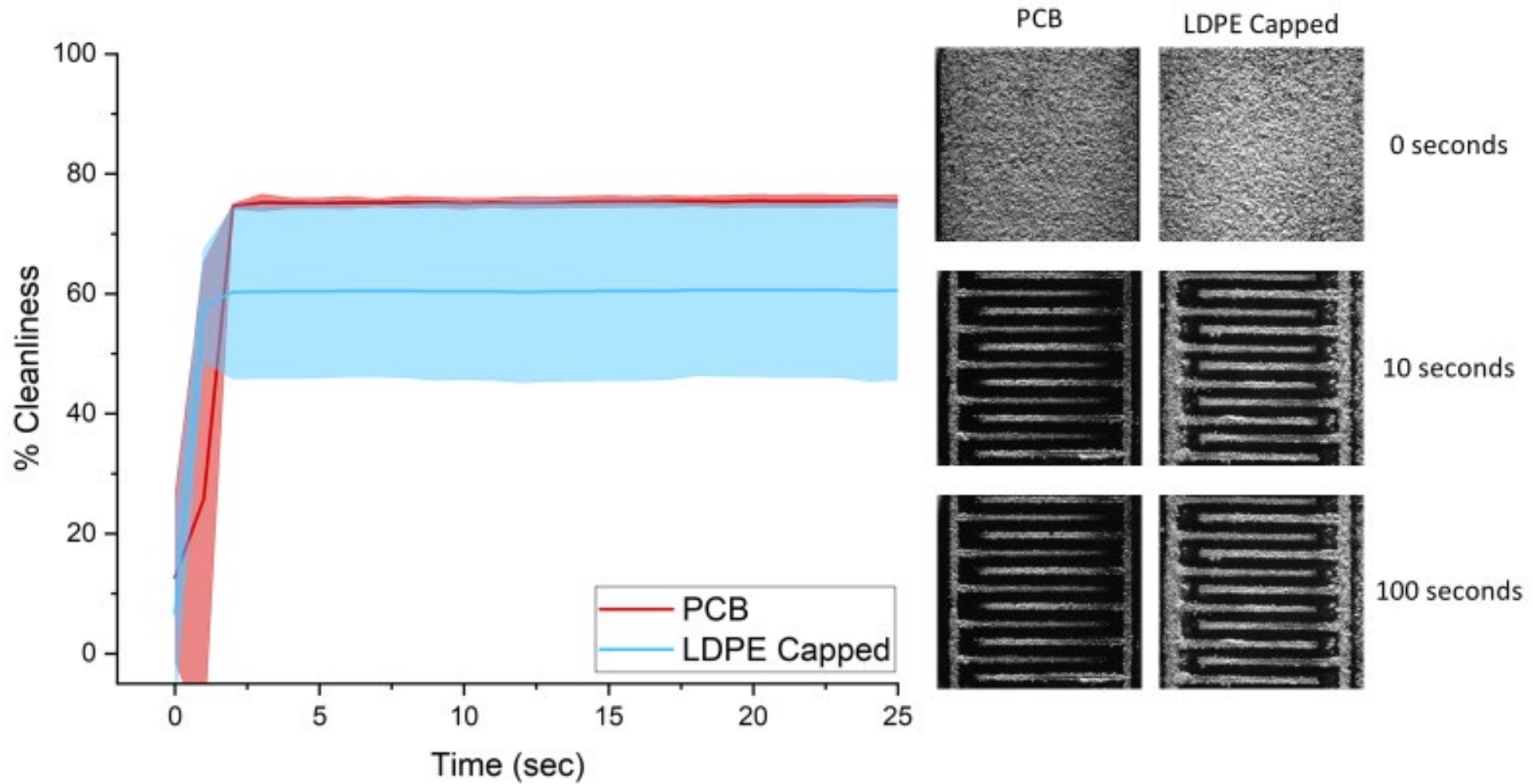


Surface Durability



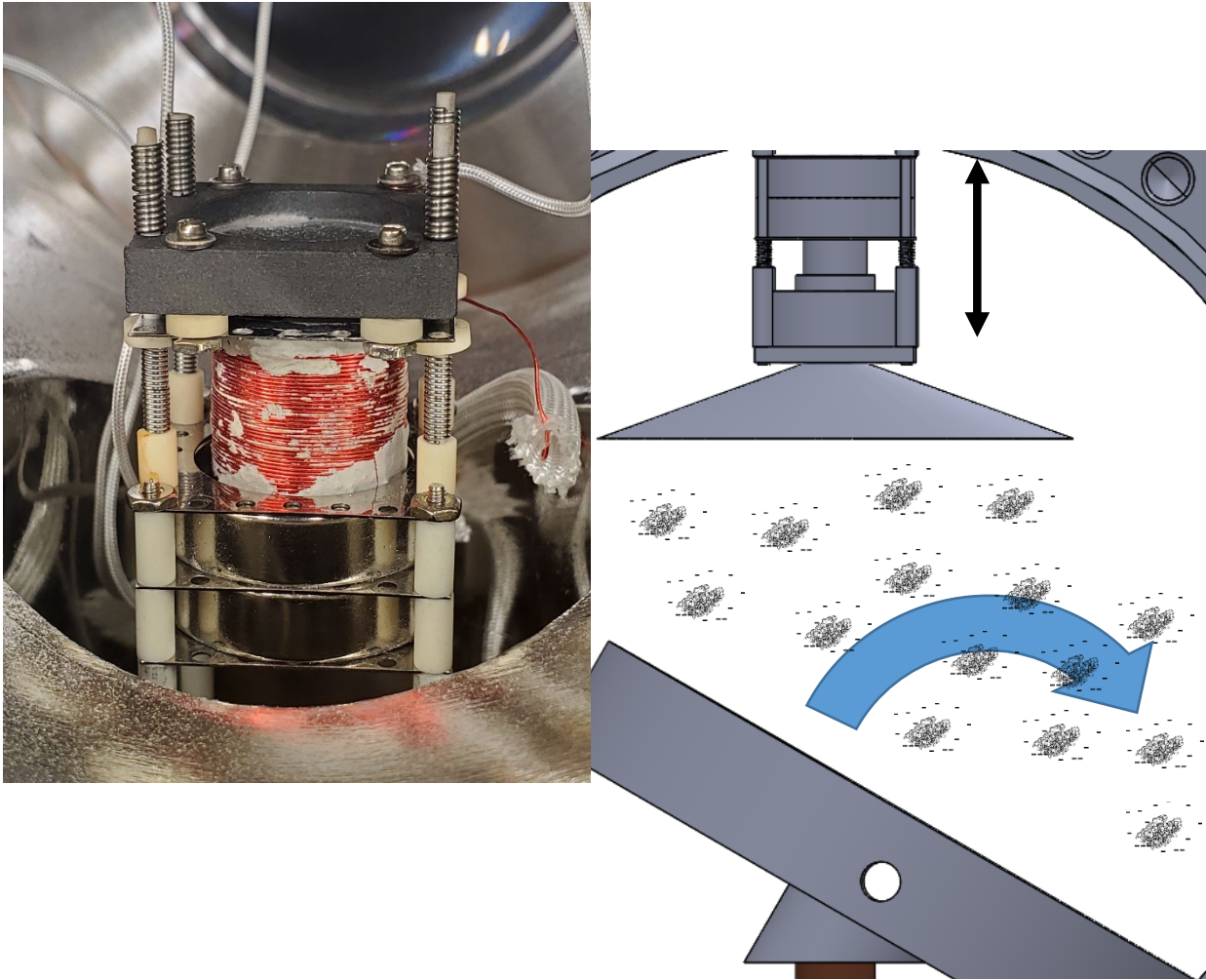


Testing Capped Devices





Dust Deposition System



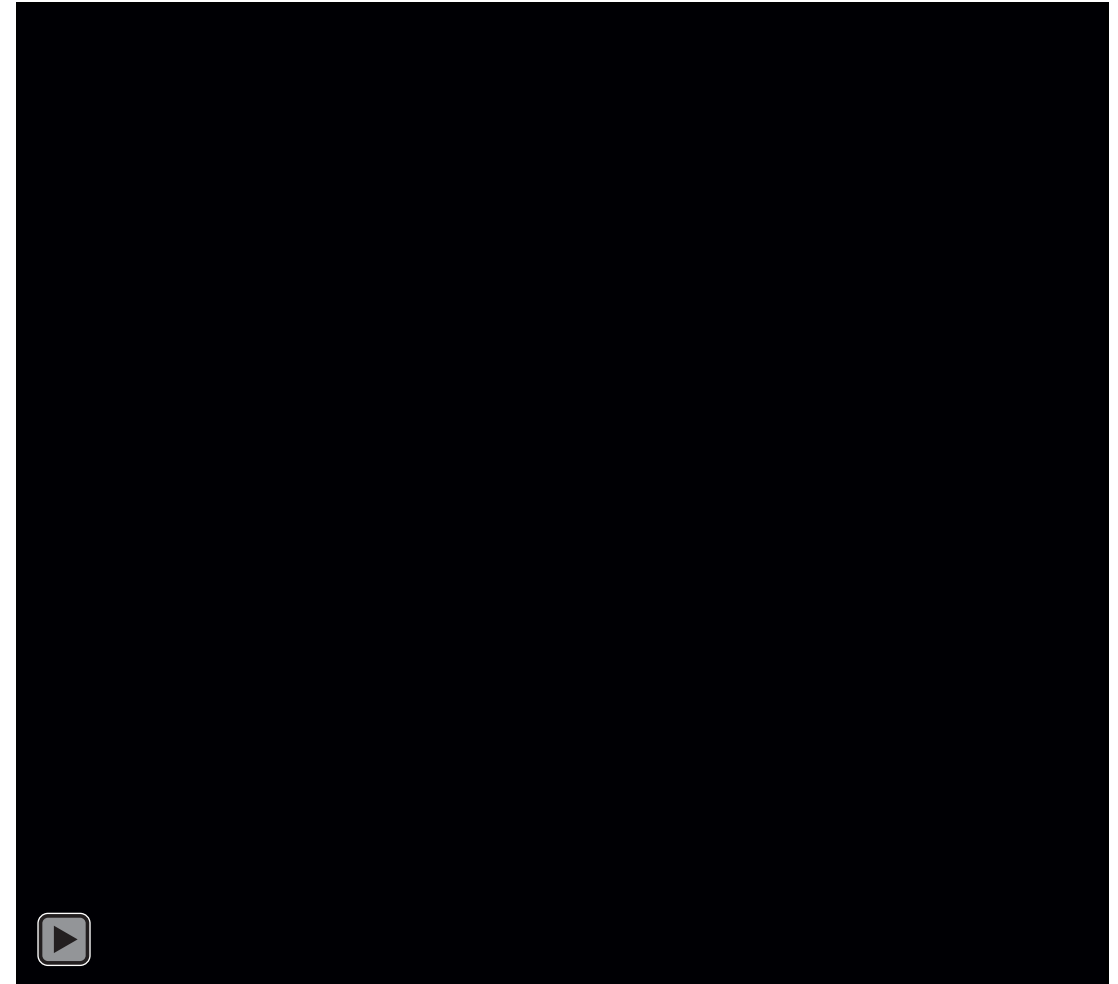
- Vibrationally driven dust hopper to deposit dust onto EDS surfaces under high vacuum conditions
- Based on a home-made voice coil and permanent magnets
- Vibrational amplitude can be controlled to vary the rate of dust deposition onto the surface below



Dust Deposition System



- Activate 2-phase EDS (1500 V)
- Initiate dust deposition with EDS activated
- After ~5 min, EDS is deactivated while dust is still being deposited
- Dust accumulates on deactivated surface for several minutes
- Finally, EDS is reactivated to clear off accumulated dust





Moving Forward



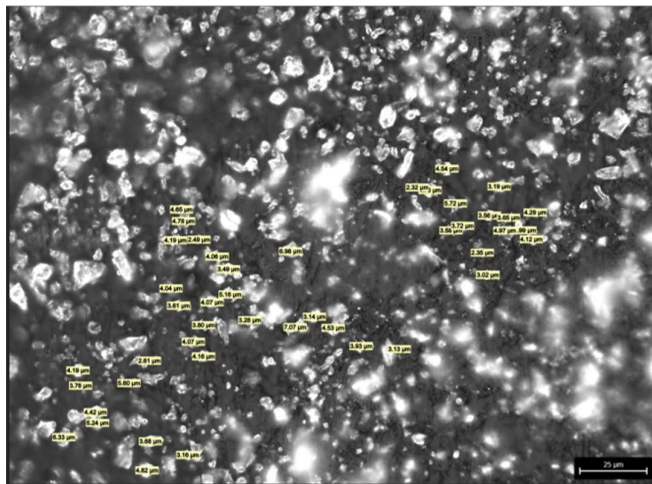
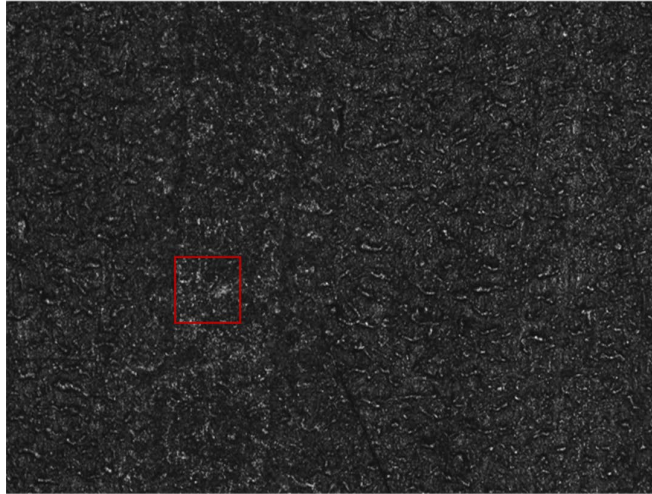
- Continue testing EDS devices by dropping charged dust grains onto an activated surface and with EDS devices in flexure.
- Explore alternative capping materials
 - nanostructured materials to reduce surface adhesion
 - improve the cleaning performance of devices for the smallest size grain fractions
- Incorporate with additional mitigation strategies such as vibrational tribocharging, and electron bombardment



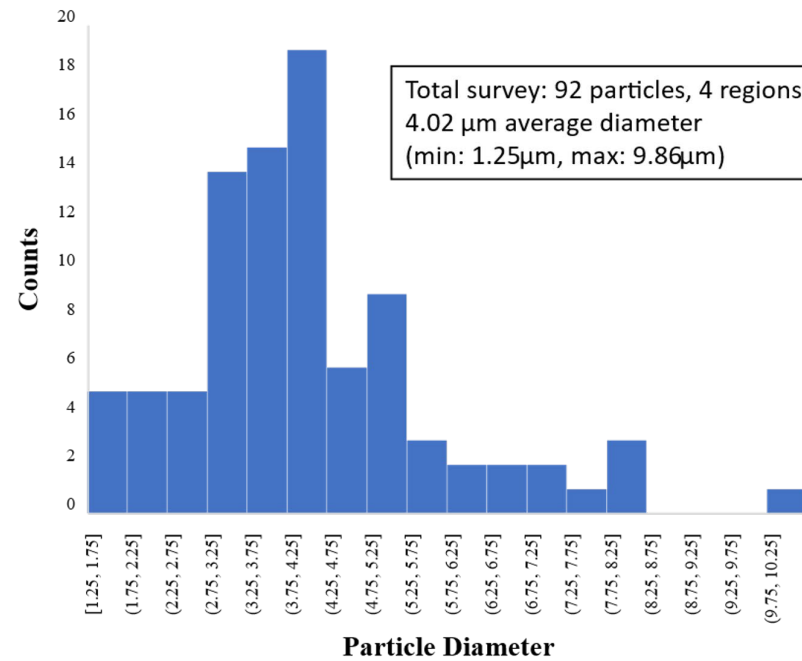
Supplemental Slides



Grain Size After EDS removal

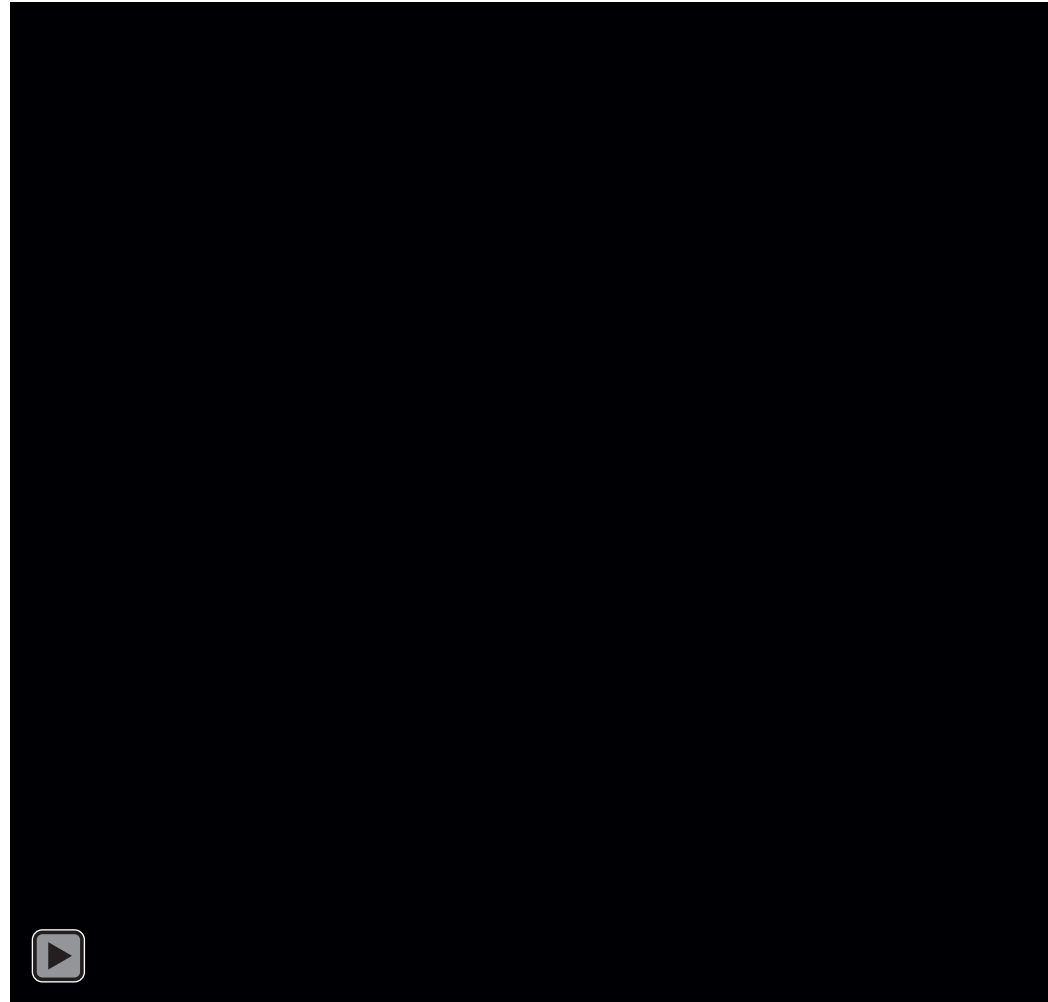


- Device – 3 phase smooth device after use, no wiping/washing/dust disturbance (outside of covered transport to microscope)
- Images - taken at 5x and 50x to show overall surface variability and measure particle size
- *Note: Only in focus particles were measured for analysis





Discharges on EDS Activation





Rough 2-phase devices + vibration

